# Supertex inc.

# 8-Channel Serial to Parallel Converter with High Voltage Push-Pull Outputs, POL, Hi-Z, and Short Circuit Detect

#### Features

- HVCMOS<sup>®</sup> technology
- Operating output voltage of 250V
- Low power level shifting from 5.0 to 250V
- Shift register speed 8.0MHz @ V<sub>DD</sub> = 5.0V
- 8 latch data outputs
- Output polarity and blanking
- Output short circuit detect
- Output high-Z control
- CMOS compatible inputs

#### Applications

- Piezoelectric transducer driver
- Braille driver
- Weaving applications
- Printer drivers
- MEMs
- Displays

# **General Description**

The HV513 is a low voltage serial to high voltage parallel converter with 8 high voltage push-pull outputs. This device has been designed to drive small capacitve loads such as piezoelectric transducers. It can also be used in any application requiring multiple high voltage outputs, with medium current source and sink capabilities.

The device consists of an 8-bit shift register, 8 latches, and control logic to perform the polarity select and blanking of the outputs. Data is shifted through the shift register on the low to high transition of the clock. A data output buffer is provided for cascading devices. Operation of the shift register is not affected by the LE, BL, POL, or the HI-Z control inputs. Transfer of data from the shift register to the latch occurs when the LE is high. The data in the latch is stored when LE is low. A high-Z (HI-Z) pin is provided to set all the outputs in a high-Z state.

All outputs have short circuit protection that detects if the outputs have reached the required output state. If output does not track the required state, then the SHORT pin will be low. This output will pulse low during the output transistion period under normal operation; see SC Timing Diagram for details.

All outputs will have a break-before-make circuitry to reduce cross-over current during output state changes.

The  $\overline{POL}$ ,  $\overline{BL}$ ,  $\overline{LE}$ , and  $\overline{HI-Z}$  inputs have an internal pull up resistor.

# **Typical Application Circuit**



### **Ordering Information**

Part Number	Package	Packing			
HV513K7-G	32-Lead QFN	400/Tray			
HV513K7-G M935	32-Lead QFN	2000/Reel			
HV513WG-G	24-Lead SOW	1000/Reel			

-G denotes a lead (Pb)-free / RoHS compliant package

# Absolute Maximum Ratings

Parameter	Value
Logic supply, V <sub>DD</sub>	-0.5V to 6.0V
High voltage supply, $V_{PP}$	$V_{\text{DD}}$ to 275V
Logic input levels	-0.5V to $V_{\text{DD}}$ +0.5V
Ground current <sup>1</sup>	0.3A
High voltage supply current <sup>1</sup>	0.25A
Continuous total power dissipation <sup>2</sup>	750mW
Operating junction temperature	-40°C to +85°C
Storage temperature range	-65°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the Package may or may not include the following marks: Si or 🎧 device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

#### Notes:

- 1. Connection to all power and ground pads is required. Duty cycle is limited by the total power dissipated in the package.
- 2. For operation above 25°C ambient derate linearly to 85°C at 12mW/°C.

### **Typical Thermal Resistance**

Package	$\boldsymbol{\theta}_{ja}$	Pa
32-Lead QFN	22°C/W	Pa
24-Lead SOW	44°C/W	

# **Pin Configuration**



### **Product Marking**



#### 32-Lead QFN



ackage may or may not include the following marks: Si or 👘

24-Lead SOW

#### **Typical Operating Conditions**

Sym	Parameter	Min	Тур	Max	Units	Conditions
V <sub>DD</sub>	Logic supply voltage	4.5	5.0	5.5	V	
V <sub>PP</sub>	High voltage supply	50	-	250	V	Note 1
V <sub>IH</sub>	High-level input voltage	V <sub>DD</sub> -0.9	-	V <sub>DD</sub>	V	
V <sub>IL</sub>	Low-level input voltage	0	-	0.9	V	
TJ	Operating junction temperature	-40	-	+85	°C	

Notes:

1. Below minimum  $V_{PP}$  the output may not switch.

2. Power-up sequence should be the following:

- 1. Connect ground
- 2. Apply  $V_{DD}$
- 3. Set all inputs (Data, CLK, Enable, etc.) to a known state
- 4. Apply V<sub>PP</sub>

Power-down sequence should be the reverse of the above

# **DC Electrical Characteristics** (Over typical operating conditions unless otherwise specified, $T_J = 25^{\circ}$ C)

Sym	Parameter		Min	Тур	Max	Units	Conditions
I <sub>DD</sub>	V <sub>DD</sub> supply current		-	-	4.0	mA	$f_{CLK} = 8.0Hz, \overline{LE} = Low$
1	Quiescent V <sub>DD</sub> supply	current	-	-	0.1	mA	All $V_{IN} = V_{DD}$
DDQ		current	-	-	2.0	IIIA	All V <sub>IN</sub> = 0V
I <sub>PP</sub>	$V_{_{PP}}$ supply current		-	-	100	μA	$V_{_{PP}}$ = 250V, f <sub>OUT</sub> = 300Hz, no load
I <sub>PPQ</sub>	Quiescent $V_{PP}$ supply	current	-	-	100	μA	$V_{_{\rm PP}}$ = 240V, outputs are static
I <sub>IH</sub>	High-level logic input	current	-	-	10	μA	V <sub>IH</sub> = V <sub>DD</sub>
			-		-10		V <sub>IL</sub> = 0V
I <sub>IL</sub>	Low-level logic input	current	-	-	-350	μA	$V_{IL} = 0V$ , for inputs w/pull-up resistors
V	High lovel output	HV <sub>OUT</sub>	140	-	-	V	$V_{_{\mathrm{PP}}}$ = 200V, $I_{_{\mathrm{HVOUT}}}$ = -20mA
V <sub>OH</sub>	High level output	Data out	V <sub>DD</sub> -1.0V	-	-	V	I <sub>DOUT</sub> = -0.1mA
		HV <sub>out</sub>	-	-	60	V	V <sub>DD</sub> = 4.5V, I <sub>HVOUT</sub> = 20mA
V <sub>OL</sub>	Low level output	Data out	-	-	1.0	V	I <sub>DOUT</sub> = 0.1mA

# **AC Electrical Characteristics** (Over typical operating conditions unless otherwise specified, $T_j = 25^{\circ}$ C)

Sym	Parameter	Min	Тур	Max	Units	Conditions
f <sub>ськ</sub>	Clock frequency	0	-	8.0	MHz	
f <sub>out</sub>	Output switching frequency (SOA limited)	-	300	-	Hz	C <sub>L</sub> = 50nF, V <sub>PP</sub> = 200V
t <sub>w</sub>	Clock width high and low	62	-	-	ns	
t <sub>su</sub>	Data setup time before clock rises	15	-	-	ns	
t <sub>H</sub>	Data hold time after clock rises	30	-	-	ns	
t <sub>wLE</sub>	Width of latch enable pulse	80	-	-	ns	
t <sub>DLE</sub>	LE delay time after rising edge of clock	35	-	-	ns	
t <sub>sle</sub>	LE setup time before rising edge of clock	40	-	-	ns	
$t_{OR}^{}, t_{OF}^{}$	HV <sub>out</sub> rise/fall time	-	-	1000	μs	C <sub>L</sub> = 100nF, V <sub>PP</sub> = 200V
t <sub>d ON/OFF</sub>	Delay time for output to start rise/fall	-	-	500	ns	
t <sub>DHL</sub>	Delay time clock to $D_{OUT}$ high to low	-	-	110	ns	C <sub>L</sub> = 15pF
t <sub>DLH</sub>	Delay time clock to $D_{OUT}$ low to high	-	-	110	ns	C <sub>L</sub> = 15pF
t <sub>R</sub> , t <sub>F</sub>	All logic inputs	-	-	5.0	ns	
t <sub>sD</sub>	Output short circuit detection	-	-	500	ns	$C_{L} = 15pF$ , Short to output fall of SHORT
t <sub>sc</sub>	Output short circuit clear	-	-	3000	ns	Short clear to output rise of SHORT
t <sub>HI-Z</sub>	Output HI-Z state	-	-	500	ns	

#### Input and Output Equivalent Circuits



### Short Circuit Detect Detail Timing



#### Note:

For  $V_{PP}$  greater than 150V:

Short detect output will flag short conditions

-  $HV_{out}$  is higher than 10V when expected low -  $HV_{out}$  is lower than  $V_{pp}$ - 100V when expected high

Short detect output will stay clear

-  $HV_{OUT}$  is lower than 2.0V when expected low -  $HV_{OUT}$  is higher than  $V_{PP}$  - 60V when expected high

#### **Switching Waveforms**



#### **Functional Block Diagram**



Not<u>e:</u>

 $\overline{POL}$ ,  $\overline{BL}$ ,  $\overline{LE}$ , and  $\overline{Hi-Z}$  have internal 20k $\Omega$  pull-up resistors.

Fun	ction	Table
	ouon	IUNIC

			Inpu	uts			Outputs					
Function	Data	CLK	LE	BL	POL	HI-Z	Shift Reg 1 28	HV Outputs 1 28	Data Out ●			
All on	Х	Х	Х	L	L	Н	• ••	Н НН	•			
All off	Х	Х	Х	L	Н	Н	• ••	L LL	•			
Invert mode	Х	Х	L	Н	L	Н	• ••	• •• (b)	•			
Load S/R	H OR L	1	L	Н	Н	Н	HorL ●●	• ••	•			
Store data in	Х	Х	L	Н	Н	Н	• ••	• ••	•			
latches	Х	Х	L	Н	L	Н	• ••	• •• (b)	•			
Transparent	L	<b>↑</b>	Н	н	Н	Н	L ••	L ••	•			
mode	Н	<b>↑</b>	Н	н	Н	Н	Н ●●	Η ●●	•			
Outputs High-Z	х	х	х	х	х	L	• ••	High impedence outputs	•			
Outputs on	Х	Х	Х	Х	Х	Н	• ••	• ••	•			

#### Notes:

 $H = high \ level, \ L = low \ level, \ X = irrelevant, \uparrow = low-to-high \ transition_$ 

• = dependent on previous stage's state before the last CLK or last  $\overline{LE}$  high.

#### Pin Description - 32-Lead QFN

Pin #	Function	Description
1		
2	NC	No internal connection
3		
4	LGND	Low voltage ground
5	HVGND	High voltage ground
6	INGIND	nigh voltage ground
7	NC	No internal connection
8	NC	
9	HV <sub>out</sub> 1	High voltage push-pull output
10	HV <sub>OUT</sub> 2	High voltage push-pull output
11	HV <sub>OUT</sub> 3	High voltage push-pull output
12	HV <sub>out</sub> 4	High voltage push-pull output
13	HV <sub>out</sub> 5	High voltage push-pull output
14	HV <sub>out</sub> 6	High voltage push-pull output
15	HV <sub>out</sub> 7	High voltage push-pull output
16	HV <sub>out</sub> 8	High voltage push-pull output
17	NC	No internal connection
18	NC	No internal connection
19		
20	VPP	High voltage supply
21	VDD	Logic supply voltage
22	DOUT	Data output
23	NC	No internal connection
24	NC	No internal connection
25	BL	Blanking pin, logic input low sets all HV <sub>OUTS</sub> low
26	NC	No internal connection
27	POL	Polarity bar input logic
28	CLK	Clock pin, shift registers shifts data on rising edge of input clock
29	LE	Latch enable bar input logic
30	SHORT	If output does not reach its required state, SHORT pin will output logic low
31	HI-Z	High impedance pin, logic input low sets all outputs in a high impedance state
32	DIN	Data input
Center Pad	VPP	Center pad is at $V_{_{PP}}$ potential. Connect to VPP or leave floating.

#### Pin Description - 24-Lead SOW

Pin #	Function	Description					
1	NC	No internal connection					
2	VDD	Logic supply voltage					
3	DOUT	Data output					
4	BL	Blanking pin, logic input LOW sets all HV <sub>OUTS</sub> low					
5	POL	Polarity bar input logic					
6	CLK	Clock pin, shift registers shifts data on rising edge of input clock					
7	LE	Latch enable bar input logic					
8	SHORT	If output does not reach its required state, SHORT pin will output logic LOW					
9	HI-Z	High impedance pin, logic input LOW sets all outputs in a high impedance state					
10	DIN	Data input					
11	LGND	Low voltage ground					
12	NC	No internal connection					
13	HVGND	High voltage ground					
14	INGIND						
15	HV <sub>OUT</sub> 1	High voltage push-pull output					
16	HV <sub>OUT</sub> 2	High voltage push-pull output					
17	HV <sub>OUT</sub> 3	High voltage push-pull output					
18	HV <sub>OUT</sub> 4	High voltage push-pull output					
19	$HV_{OUT}5$	High voltage push-pull output					
20	HV <sub>out</sub> 6	High voltage push-pull output					
21	HV <sub>out</sub> 7	High voltage push-pull output					
22	HV <sub>OUT</sub> 8	High voltage push-pull output					
23	VPP	High voltage supply					
24	VEE						

# 32-Lead QFN Package Outline (K7) 6.00x6.00mm body, 0.80mm height (max), 0.50mm pitch



#### Notes:

- 1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
- 2. The 4 corner pads are for mechanical placement only, they are not internally connected.

Symbo	ol	Α	A1	b	D	D1	E	E1	е	e1	e2	L	L1	LC	LC1	
Dimension (mm)	MIN	0.70	0.00	0.20	5.90	3.20	5.90	4.30		0.50 1.00 BSC REF	4 00	0.075	0.20		0.20	0.25
	NOM	0.75	-	0.30	6.00	3.30	6.00	4.40			0.975 REF	0.30	0.10 REF	0.30	0.35	
	MAX	0.80	0.05	0.40	6.10	3.40	6.10	4.50	200			0.40		0.40	0.45	

#### Drawings not to scale.

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### 24-Lead SOW (Wide Body) Package Outline (WG) 15.40x7.50 body, 2.65mm height (max), 1.27mm pitch



#### Note:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	ol	Α	A1	A2	b	D	Е	E1	е	h	L	L1	L2	θ	θ1
Dimension (mm)	MIN	2.15*	0.10	2.05	0.31	15.20*	9.97*	7.40*		0.25	0.40			<b>0</b> 0	<b>5</b> °
	NOM	-	-	-	-	15.40	10.30	7.50	1.27 BSC	-	- 1.40	0.25 BSC	-	-	
()	MAX	2.65	0.30	2.55*	0.51	15.60*	10.63*	7.60*		0.75	1.27			<b>8</b> 0	15 <sup>0</sup>

JEDEC Registration MS-013, Variation AD, Issue E, Sep. 2005.

\* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

Supertex Doc. #: DSPD-24SOWWG, Version E041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <u>http://www.supertex.com/packaging.html</u>.)

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